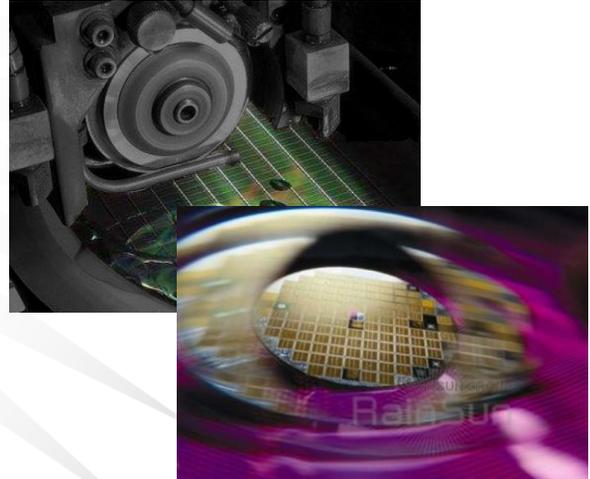
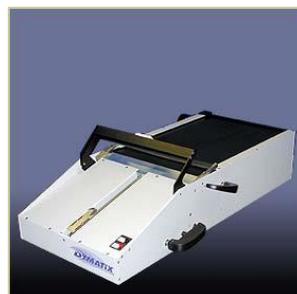
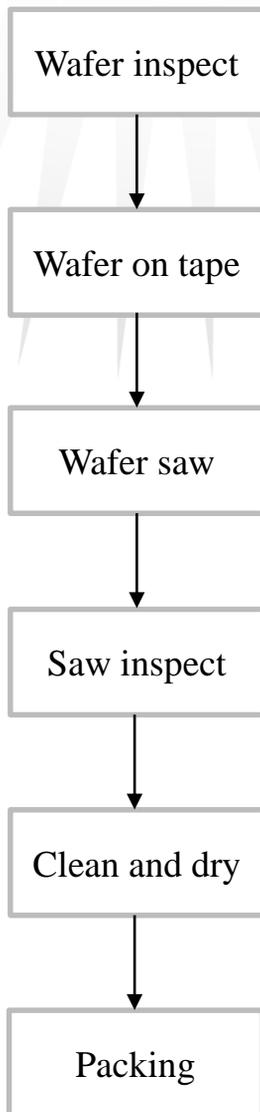


Wafer Die Saw/ Custom process

- 4 inch to 6 inch wafer die saw .
- Diode wafer and general IC wafer.
- minimum saw cutting width 25um.
- Saw equipment using Disco automatic process.
- High quality and efficient.



Operation process:



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